

High Performance 3D Post-reflow AOI Solution



High-throughput 3D AOI technology

Standard Y-axis dual-drive with high precision

Powerful offline programming & real-time debugging functions

Rich algorithm functions

With AI functions to reduce misjudgment & improve detection capability

3D AOI

*** Unique light source and imaging system**

- 12 million CXP high-speed industrial cameras, super fast
- 4-way projection DLP shadowless projector

*** Standard Y-axis dual-drive with high precision**

Benchmark point positioning + pad positioning + main body positioning

*** Powerful offline programming and real-time debugging functions**

No need to stop the line, directly debug without affecting production efficiency

*** Shared inspection program and component library**

Inspection programs and component libraries are saved on the server and can be shared by multiple devices

*** Rich algorithm functions**

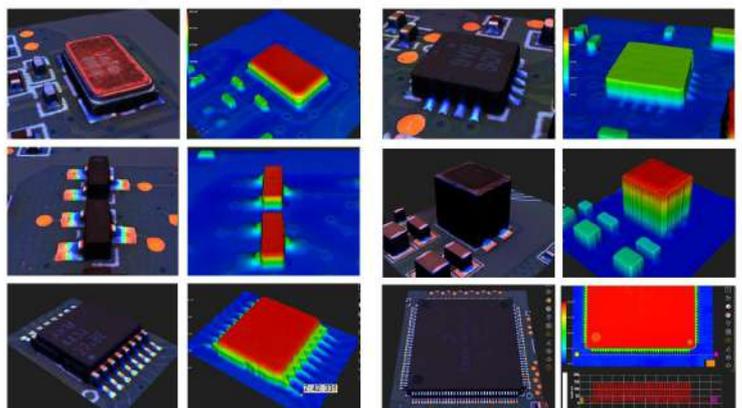
High detection rate, large selectivity

*** Optimal solution for board bending correction**

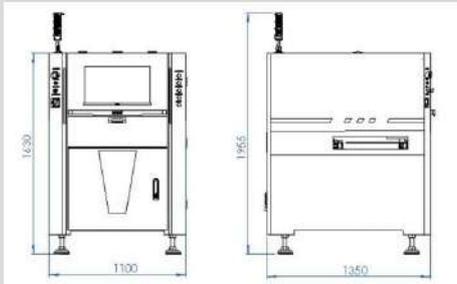
Equipped with Z-axis mechanism to perfectly solve the problem of board bending

*** Equipped with AI function (AI logical algorithm)**

Easy programming with advanced AI technology



Technical Specifications



Dimensions: 1100mm (L) × ≤1350 (W) × ≤1630mm (H)

Weight: Around 1300 kg

Inspection Item	SMT components
Inspection Defects	Missing components, misalignment, polarity, lifted leads, sideward, tombstone effect, solder joint defects, solder balls, contamination, foreign objects, and scratches.
Camera	12MP/25MP industrial camera (Optional)
Resolution	5μm/10μm/15μm (Optional)
Lighting	RGBW LED multi-angle light source
Inspection Speed	8.6cm ² /s 34.3cm ² /s 77.1cm ² /s @ 12M
PCB Weight	< 4.0kg (with components on board)
PCB Size	50*50~510*460mm
PCB Thickness	Thickness: 0.4-6mm
PCB Clearance	3mm
Upper/Lower Transport Clearance	45mm
Detection Height	Maximum measurable height of 30mm
Board Bending Correction	±3mm
Transport Height	900±50mm
Board Bending Correction Method	Adjusting the height along the Z-axis for correction for the bending of the circuit board.
Transport Method	Conveyor belt
PCB Fixation	Fixed by track rail
Y Axis Drive	Y-axis gantry dual motor drive
Track Width Adjustment	Automatic adjustment
Arrival Detection Mode	Sensor detection
Industrial Computer	Intel I7-13700K processor\8*16GB\1*1TB SSD\1*6TB SATA 3.5"HDD
Gigabit Network Card	Intel® Ethernet Controller I225-V \ I219-V
Graphic Card	NVIDIA GeForce RTX 3060
Operation System	WIN10 64bit
Operation Software	ST VISION
Interface	MES
Operation Method	Keyboard, mouse, buttons
Language	English, Chinese